

SGM8632C 480µA, 6MHz, Rail-to-Rail I/O CMOS Operational Amplifier

GENERAL DESCRIPTION

The SGM8632C is a dual, low voltage, low noise and low power operational amplifier, which can operate from 2V to 5.5V single supply, while consuming only $480\mu A$ quiescent current per amplifier at 5V.

The SGM8632C features a 3.5mV maximum input offset voltage. The minimum input common mode voltage is within 0.1V below the negative rail, and the output swing is rail-to-rail with heavy loads. It exhibits a high gain-bandwidth product of 6MHz and a slew rate of 3.7V/µs. These specifications make the operational amplifier appropriate for various applications.

The SGM8632C is available in a Green MSOP-8 package. It is specified over the extended industrial temperature range (-40°C to +125°C).

FEATURES

Input Offset Voltage: 3.5mV (MAX)High Gain-Bandwidth Product: 6MHz

• High Slew Rate: 3.7V/µs

• Settling Time to 0.1% with 2V Step: 0.5µs

Overload Recovery Time: 0.9µs
Low Noise: 13nV/√Hz at 1kHz

Rail-to-Rail Input and Output

Supply Voltage Range: 2V to 5.5V

Input Voltage Range: -0.1V to +5.6V with V_S = 5.5V

• Low Supply Current: 480µA/Amplifier (TYP)

Available in a Green MSOP-8 Package

APPLICATIONS

Sensors

Audio

Active Filters

A/D Converters

Communications

Test Equipment

Cellular and Cordless Phones

Laptops and PDAs

Photodiode Amplification

Battery-Powered Instrumentation

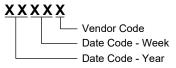


PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION	
SGM8632C	MSOP-8	-40°C to +125°C	SGM8632CXMS8G/TR	SGM8632 XMS XXXXX	Tape and Reel, 4000	

MARKING INFORMATION

NOTE: XXXXX = Date Code and Vendor Code.



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, +V _S to -V _S	6V
Input Common Mode Voltage Range	
(-V _S) - 0.3\	/ to (+Vs) + 0.3V
Package Thermal Resistance @ T _A = +25°C	
MSOP-8, θ _{JA}	182°C/W
Junction Temperature	+150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (Soldering, 10s)	+260°C
ESD Susceptibility	
HBM	V0008
MM	400V
CDM	1000V

RECOMMENDED OPERATING CONDITIONS

Operating Temperature Range-40°C to +125°C

OVERSTRESS CAUTION

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

ESD SENSITIVITY CAUTION

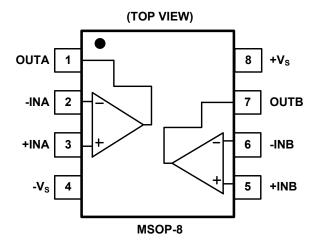
This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures

can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

PIN CONFIGURATION



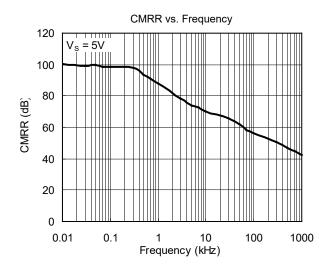
ELECTRICAL CHARACTERISTICS

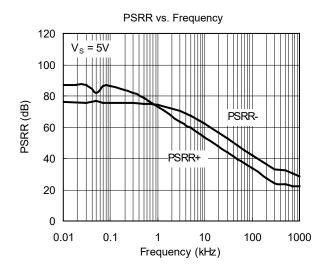
(At $T_A = +25$ °C, $V_S = 5V$, $V_{CM} = V_S/2$, $R_L = 600\Omega$, unless otherwise noted.)

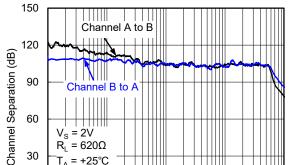
		TYP	M	IIN/MAX O	VER TEM	PERATUR	E
PARAMETER	CONDITIONS	+25℃	+25℃	-40°C to +85°C	-40°C to +125°C	UNITS	MIN/ MAX
Input Characteristics							
Input Offset Voltage (Vos)		0.9	3.5	3.7	3.8	mV	MAX
Input Bias Current (I _B)		1				pА	TYP
Input Offset Current (I _{OS})		1				pА	TYP
Input Common Mode Voltage Range (V _{CM})	V _S = 5.5V	-0.1 to 5.6				V	TYP
Common Mode Rejection Retin (CMRR)	V _S = 5.5V, V _{CM} = -0.1V to 4V	84	68	67	66	dB	MIN
Common Mode Rejection Ratio (CMRR)	V _S = 5.5V, V _{CM} = -0.1V to 5.6V	76				dB	MIN
Ones Leen Voltage Cain (A.)	$R_L = 600\Omega$, $V_{OUT} = 0.15V$ to 4.85V	86	79	73	69	dB	MIN
Open-Loop Voltage Gain (A _{OL})	$R_L = 10k\Omega$, $V_{OUT} = 0.05V$ to 4.95V	103				dB	MIN
Input Offset Voltage Drift (ΔV _{OS} /ΔT)		2.4				μV/°C	TYP
Output Characteristics							
Outsid Voltage Outside from Dail	$R_L = 600\Omega$	0.079				V	TYP
Output Voltage Swing from Rail	$R_L = 10k\Omega$	0.007				V	TYP
Output Current (I _{OUT})		58	40	30	26	mA	MIN
Closed-Loop Output Impedance	f = 200kHz, G = 1	5.4				Ω	TYP
Power Supply							
On a mating at Maltagrap Day are		2	2	2	2	V	MIN
Operating Voltage Range		5.5	5.5	5.5	5.5	V	MAX
Power Supply Rejection Ratio (PSRR)	$V_S = 2V \text{ to } 5.5V, V_{CM} = (-V_S) + 0.5V$	84	69	68	67	dB	MIN
Quiescent Current/Amplifier (IQ)	I _{OUT} = 0	480	620	720	790	μΑ	MAX
Dynamic Performance							
Gain-Bandwidth Product (GBP)		6				MHz	TYP
Phase Margin (φ ₀)		63				0	TYP
Full Power Bandwidth (BW _P)	<1% distortion	250				kHz	TYP
Slew Rate (SR)	G = 1, 2V output step	3.7				V/µs	TYP
Settling Time to 0.1% (t _S)	G = 1, 2V output step	0.5				μs	TYP
Overload Recovery Time	V _{IN} × Gain = V _S	0.9				μs	TYP
Noise Performance						•	
Voltage Noise Density (en)	f = 1kHz	13				nV/√Hz	TYP

TYPICAL PERFORMANCE CHARACTERISTICS

At T_A = +25°C, V_{CM} = $V_S/2$, R_L = 600 Ω , unless otherwise noted.







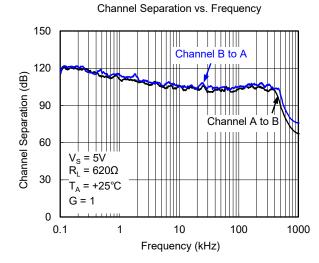
10

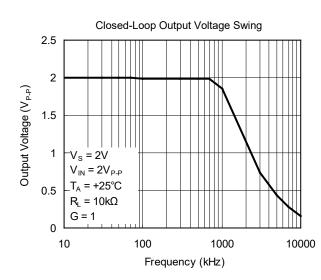
Frequency (kHz)

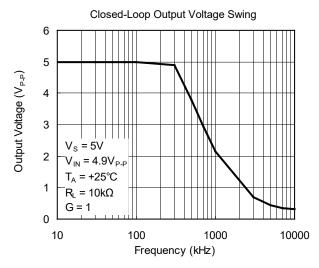
100

1000

Channel Separation vs. Frequency







30

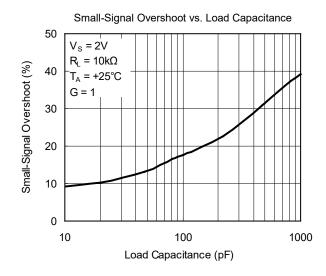
0

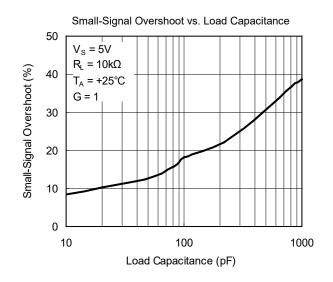
0.1

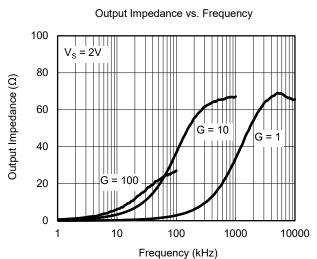
T_A = +25°C

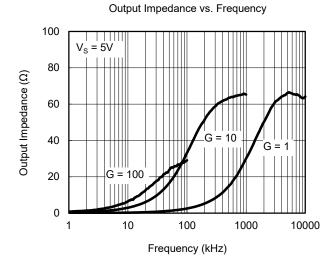
G = 1

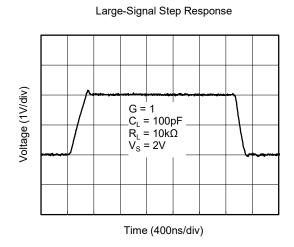
At T_A = +25°C, V_{CM} = $V_S/2$, R_L = 600 Ω , unless otherwise noted.

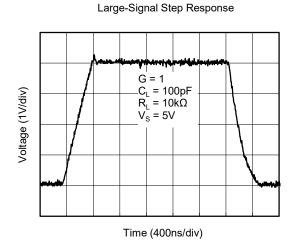




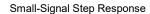


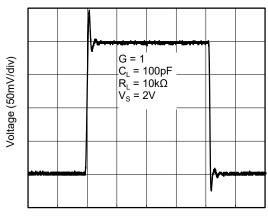






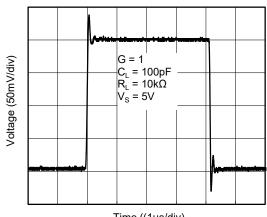
At T_A = +25°C, V_{CM} = $V_S/2$, R_L = 600 Ω , unless otherwise noted.





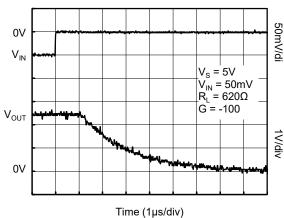
Time (1µs/div)

Small-Signal Step Response

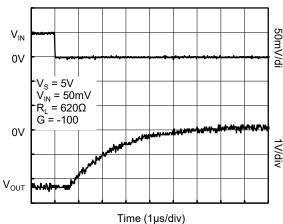


Time ((1µs/div)

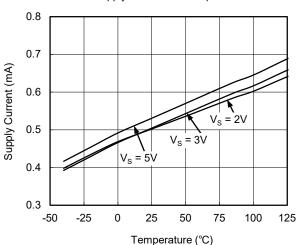
Positive overload Recovery



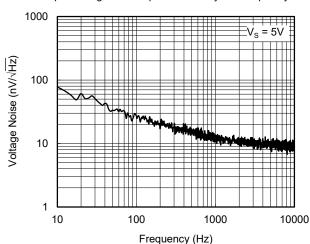
Negative Overload Recovery



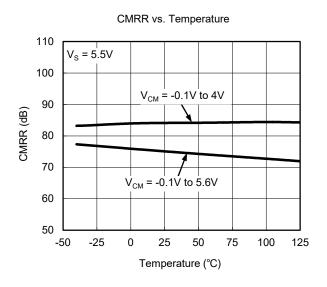
Supply Current vs. Temperature

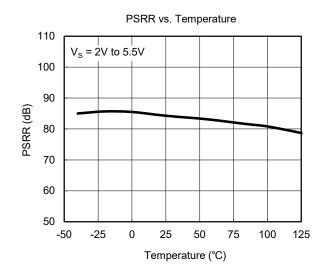


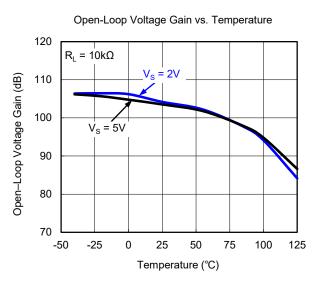
Input Voltage Noise Spectral Density vs. Frequency

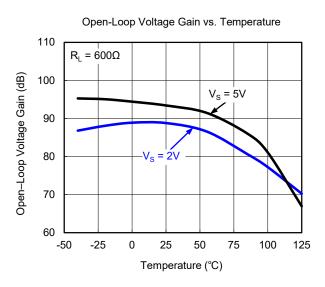


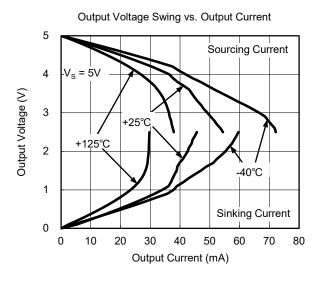
At T_A = +25°C, V_{CM} = $V_S/2$, R_L = 600 Ω , unless otherwise noted.

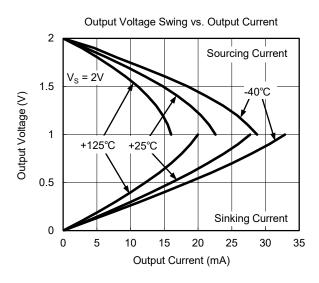




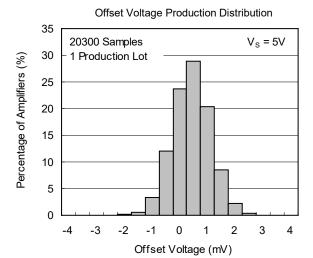








At T_A = +25°C, V_{CM} = $V_S/2$, R_L = 600 Ω , unless otherwise noted.



APPLICATION INFORMATION

Rail-to-Rail Input

When SGM8632C works at the power supply between 2V and 5.5V, the input common mode voltage range is from (-V_S) - 0.1V to (+V_S) + 0.1V. In Figure 1, the ESD diodes between the inputs and the power supply rails will clamp the input voltage not to exceed the rails.

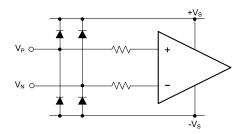


Figure 1. Input Equivalent Circuit

Rail-to-Rail Output

The SGM8632C supports rail-to-rail output operation. In single power supply application, for example, when $+V_S = 5V$, $-V_S = GND$, $10k\Omega$ load resistor is tied from OUT pin to ground, the typical output swing range is from 0.007V to 4.993V.

Driving Capacitive Loads

The SGM8632C is designed for unity-gain stable for capacitive load up to 1000pF. If greater capacitive load must be driven in application, the circuit in Figure 2 can be used. In this circuit, the IR drop voltage generated by $R_{\rm ISO}$ is compensated by feedback loop.

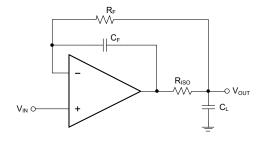


Figure 2. Circuit to Drive Heavy Capacitive Load

Power Supply Decoupling and Layout

A clean and low noise power supply is very important in amplifier circuit design, besides of input signal noise, the power supply is one of important source of noise to the amplifier through $+V_S$ and $-V_S$ pins. Power supply bypassing is an effective method to clear up the noise at power supply, and the low impedance path to ground of decoupling capacitor will bypass the noise to GND. In application, $10\mu F$ ceramic capacitor paralleled with $0.1\mu F$ or $0.01\mu F$ ceramic capacitor is used in Figure 3. The ceramic capacitors should be placed as close as possible to $+V_S$ and $-V_S$ power supply pins.

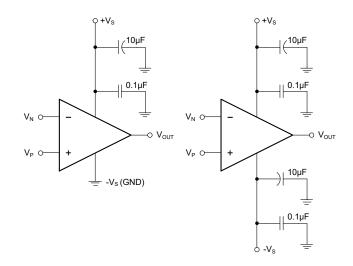


Figure 3. Amplifier Power Supply Bypassing

Grounding

In low speed application, one node grounding technique is the simplest and most effective method to eliminate the noise generated by grounding. In high speed application, the general method to eliminate noise is to use a complete ground plane technique, and the whole ground plane will help distribute heat and reduce EMI noise pickup.

Reduce Input-to-Output Coupling

To reduce the input-to-output coupling, the input traces must be placed as far away from the power supply or output traces as possible. The sensitive trace must not be placed in parallel with the noisy trace in same layer. They must be placed perpendicularly in different layers to reduce the crosstalk. These PCB layout techniques will help to reduce unwanted positive feedback and noise.

APPLICATION INFORMATION (continued)

Typical Application Circuits

Difference Amplifier

The circuit in Figure 4 is a design example of classical difference amplifier. If $R_4/R_3 = R_2/R_1$, then $V_{OUT} = (V_P - V_N) \times R_2/R_1 + V_{REF}$.

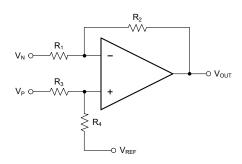


Figure 4. Difference Amplifier

High Input Impedance Difference Amplifier

The circuit in Figure 5 is a design example of high input impedance difference amplifier, the added amplifiers at the input are used to increase the input impedance and eliminate drawback of low input impedance in Figure 4.

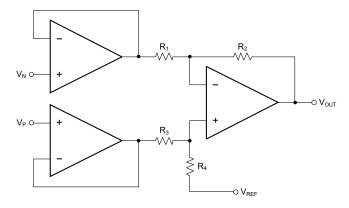


Figure 5. High Input Impedance Difference Amplifier

Active Low-Pass Filter

The circuit in Figure 6 is a design example of active low-pass filter, the DC gain is equal to $-R_2/R_1$ and the -3dB corner frequency is equal to $1/2\pi R_2C$. In this design, the filter bandwidth must be less than the bandwidth of the amplifier, the resistor values must be selected as low as possible to reduce ringing or oscillation generated by the parasitic parameters in PCB layout.

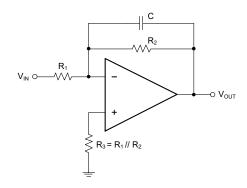


Figure 6. Active Low-Pass Filter

480µA, 6MHz, Rail-to-Rail I/O CMOS Operational Amplifier

SGM8632C

REVISION HISTORY

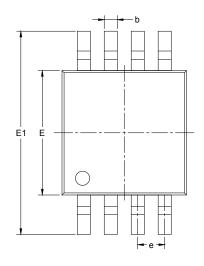
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

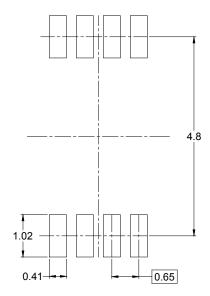
Changes from Original (NOVEMBER 2017) to REV.A

Page

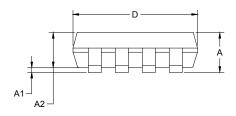


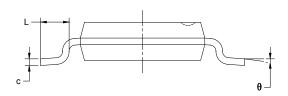
PACKAGE OUTLINE DIMENSIONS MSOP-8





RECOMMENDED LAND PATTERN (Unit: mm)

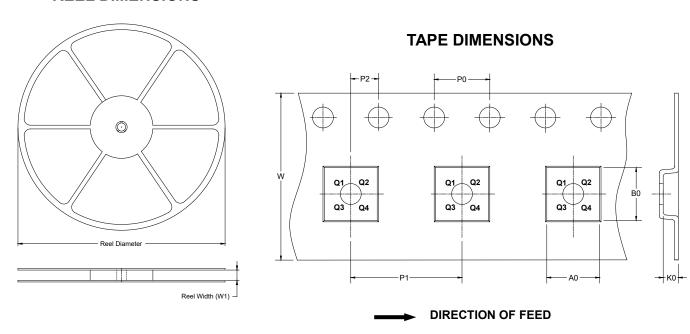




Symbol		nsions meters	Dimensions In Inches		
	MIN	MAX	MIN	MAX	
Α	0.820	1.100	0.032	0.043	
A1	0.020	0.150	0.001	0.006	
A2	0.750	0.950	0.030	0.037	
b	0.250	0.380	0.010	0.015	
С	0.090	0.230	0.004	0.009	
D	2.900	3.100	0.114	0.122	
E	2.900	3.100	0.114	0.122	
E1	4.750	5.050	0.187	0.199	
е	0.650 BSC 0.400 0.800		0.026	BSC	
L			0.016	0.031	
θ	0°	6°	0°	6°	

TAPE AND REEL INFORMATION

REEL DIMENSIONS

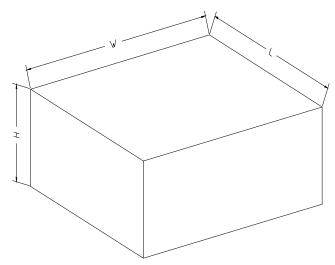


NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
MSOP-8	13"	12.4	5.20	3.30	1.50	4.0	8.0	2.0	12.0	Q1

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13"	386	280	370	5



单击下面可查看定价,库存,交付和生命周期等信息

>>SGMICRO(圣邦微电子)